

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A magnetic disk substrate polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition.

2. (Original) The polishing composition according to claim 1, wherein the abrasive is colloidal silica.

3. (Currently Amended) The polishing composition according to claim 1, ~~which is used for polishing a~~ wherein said magnetic disk substrate ~~having~~ has Ni element on a surface thereof.

4. (Currently Amended) A process for reducing a surface defect of a magnetic disk substrate comprising applying to a magnetic disk substrate or a polishing pad a polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad.

5. (Currently Amended) A process for manufacturing a magnetic disk substrate comprising a polishing step comprising applying to a magnetic disk substrate or a polishing pad a

polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad.

6. (Original) The process according to claim 5, wherein the polishing step is a finishing step of a surface polishing.

7. (New) The polishing composition according to claim 1, wherein the abrasive comprises silica particles and a content of the abrasive is 1 to 15% by weight.

8. (New) The polishing composition according to claim 1, wherein copper (Cu) is contained in an amount of 0.07 mg or less per kg of the polishing composition.

9. (New) The polishing composition according to claim 1, wherein a pH of the polishing composition is 4.0 or less.

10. (New) The process according to claim 4, wherein the abrasive comprises silica particles and a content of the abrasive is 1 to 15% by weight.

11. (New) The process according to claim 4, wherein copper (Cu) is contained in an amount of 0.07 mg or less per kg of the polishing composition.

12. (New) The process according to claim 4, wherein a pH of the polishing composition is 4.0 or less.

13. (New) The process according to claim 4, wherein members to be contacted with the polishing composition in the polishing step are made of a metal coated with a resin or made of a resin.

14. (New) The process according to claim 5, wherein the abrasive comprises silica particles and a content of the abrasive is 1 to 15% by weight.

15. (New) The process according to claim 5, wherein copper (Cu) is contained in an amount of 0.07 mg or less per kg of the polishing composition.

16. (New) The process according to claim 5, wherein a pH of the polishing composition is 4.0 or less.

17. (New) The process according to claim 5, wherein members to be contacted with the polishing composition in the polishing step are made of a metal coated with a resin or made of a resin.